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Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2016 [Approved on 26 January 2023, 08:01 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.9%	Nickel REACH Article 67 Exemption	7440-02-0	1%
			LEAD MONOOXIDE Exempt from other regulatory requirements EU RoHS Exemption 7(c)-I Exempt from other regulatory requirements	1317-36-8	5%
			Gold	7440-57-5	11.5%
			Silicon oxide	11126-22-0	20%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	0.4%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	51.4%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			3,5,3',5'-TETRABROMOBISPHENOL A Exempt from other regulatory requirements	79-94-7	0.99%
			Epoxy resin 89	26335-32-0	27.61%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
			Quartz sand	60676-86-0	70.3%
Leadfinish	Tin plating	1.7%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	44.6%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-221AC/SMAF	DO-221AC/SMAF	0.07	g